

METHOD OF FABRICATING SEMICONDUCTOR HAVING THROUGH HOLE

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ABSTRACT OF THE DISCLOSURE

The semiconductor device includes a semiconductor chip, a tape for mounting the semiconductor chip thereto, an adhesive resin layer interposed between the semiconductor chip and the tape, and solder balls attached to the tape. The method of fabricating the semiconductor chip comprises the step of forming at least one hole in the tape, after fixing the semiconductor chip to the tape through the adhesive resin layer. Also, the TAB tape is made of polyimide having high water permeability.

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